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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	ST7
Core Size	8-Bit
Speed	8MHz
Connectivity	SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	32
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	3.8V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LQFP
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/st72f324j6t6

3 REGISTER & MEMORY MAP

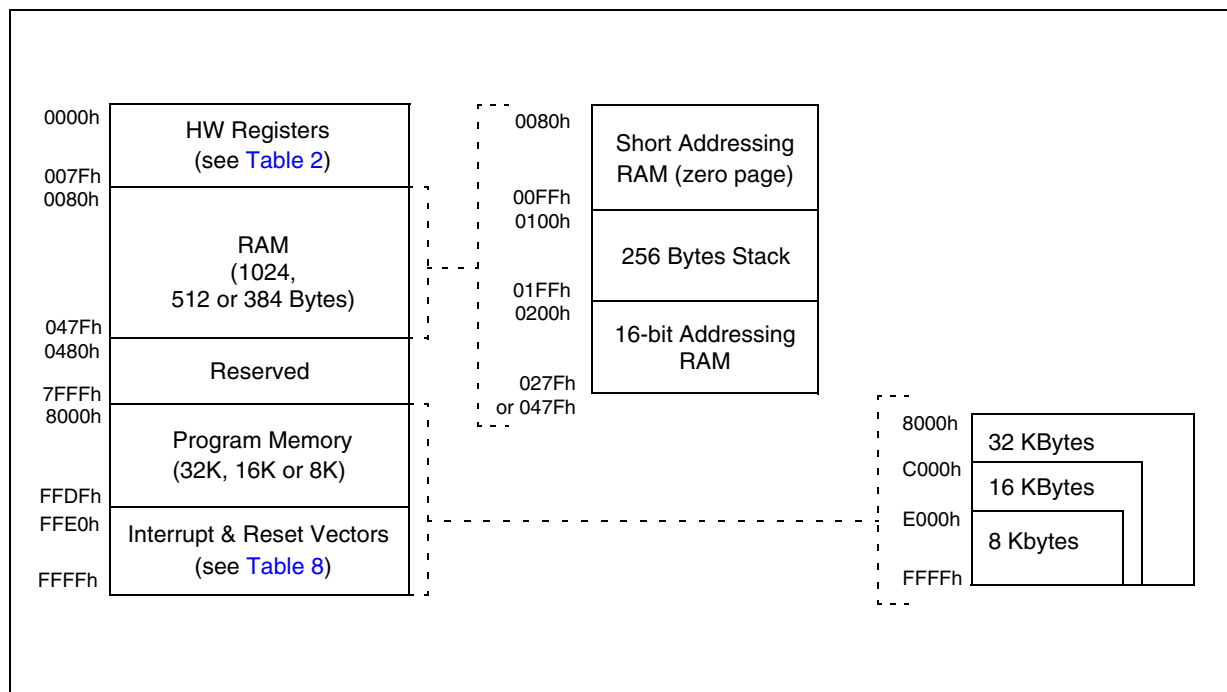
As shown in [Figure 5](#), the MCU is capable of addressing 64K bytes of memories and I/O registers.

The available memory locations consist of 128 bytes of register locations, up to 1024 bytes of RAM and up to 32 Kbytes of user program memory. The RAM space includes up to 256 bytes for the stack from 0100h to 01FFh.

The highest address bytes contain the user reset and interrupt vectors.

IMPORTANT: Memory locations marked as “Reserved” must never be accessed. Accessing a reserved area can have unpredictable effects on the device.

Figure 5. Memory Map



FLASH PROGRAM MEMORY (Cont'd)

4.5 ICP (In-Circuit Programming)

To perform ICP the microcontroller must be switched to ICC (In-Circuit Communication) mode by an external controller or programming tool.

Depending on the ICP code downloaded in RAM, Flash memory programming can be fully customized (number of bytes to program, program locations, or selection serial communication interface for downloading).

When using an STMicroelectronics or third-party programming tool that supports ICP and the specific microcontroller device, the user needs only to implement the ICP hardware interface on the application board (see [Figure 7](#)). For more details on the pin locations, refer to the device pinout description.

4.6 IAP (In-Application Programming)

This mode uses a BootLoader program previously stored in Sector 0 by the user (in ICP mode or by plugging the device in a programming tool).

This mode is fully controlled by user software. This allows it to be adapted to the user application, (user-defined strategy for entering programming mode, choice of communications protocol used to fetch the data to be stored, etc.). For example, it is

possible to download code from the SPI, SCI, USB or CAN interface and program it in the Flash. IAP mode can be used to program any of the Flash sectors except Sector 0, which is write/erase protected to allow recovery in case errors occur during the programming operation.

4.7 Related Documentation

For details on Flash programming and ICC protocol, refer to the ST7 Flash Programming Reference Manual and to the ST7 ICC Protocol Reference Manual.

4.7.1 Register Description

FLASH CONTROL/STATUS REGISTER (FCSR)

Read/Write

Reset Value: 0000 0000 (00h)

7							0
0	0	0	0	0	0	0	0

This register is reserved for use by Programming Tool software. It controls the Flash programming and erasing operations.

Table 4. Flash Control/Status Register Address and Reset Value

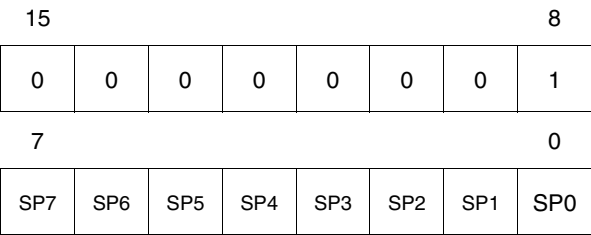
Address (Hex.)	Register Label	7	6	5	4	3	2	1	0
0029h	FCSR Reset Value	0	0	0	0	0	0	0	0

CENTRAL PROCESSING UNIT (Cont'd)

Stack Pointer (SP)

Read/Write

Reset Value: 01 FFh



The Stack Pointer is a 16-bit register which is always pointing to the next free location in the stack. It is then decremented after data has been pushed onto the stack and incremented before data is popped from the stack (see Figure 9).

Since the stack is 256 bytes deep, the 8 most significant bits are forced by hardware. Following an MCU Reset, or after a Reset Stack Pointer instruction (RSP), the Stack Pointer contains its reset value (the SP7 to SP0 bits are set) which is the stack higher address.

The least significant byte of the Stack Pointer (called S) can be directly accessed by a LD instruction.

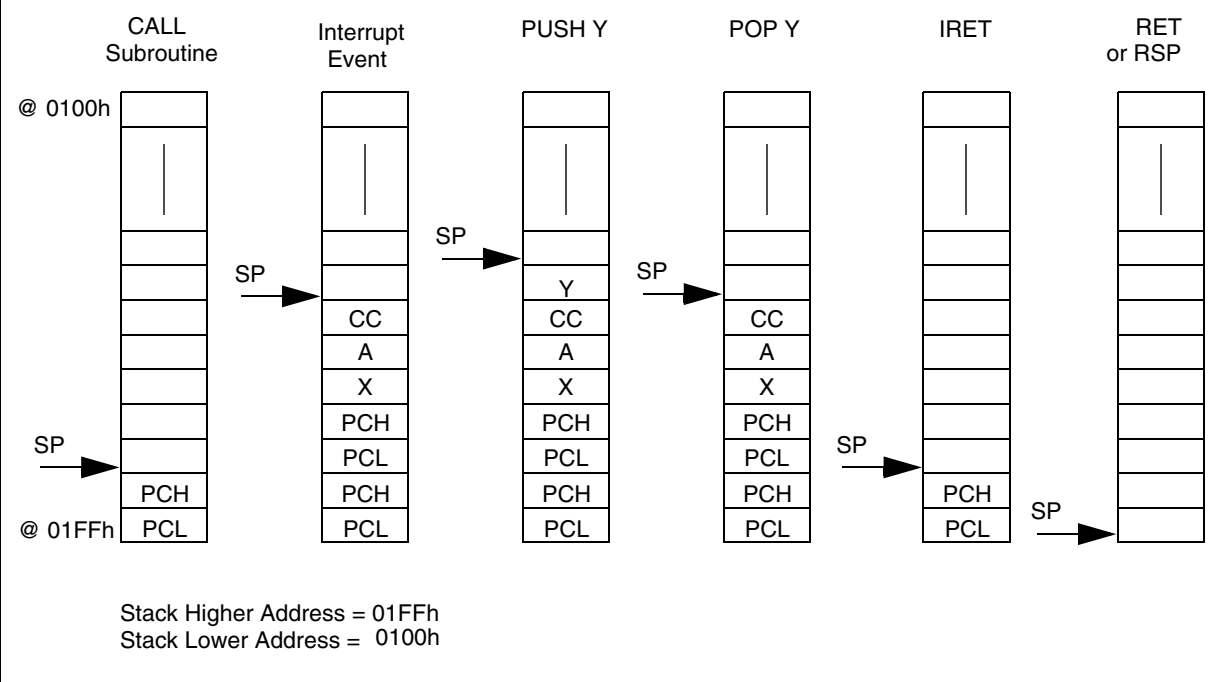
Note: When the lower limit is exceeded, the Stack Pointer wraps around to the stack upper limit, without indicating the stack overflow. The previously stored information is then overwritten and therefore lost. The stack also wraps in case of an under-flow.

The stack is used to save the return address during a subroutine call and the CPU context during an interrupt. The user may also directly manipulate the stack by means of the PUSH and POP instructions. In the case of an interrupt, the PCL is stored at the first location pointed to by the SP. Then the other registers are stored in the next locations as shown in Figure 9.

- When an interrupt is received, the SP is decremented and the context is pushed on the stack.
- On return from interrupt, the SP is incremented and the context is popped from the stack.

A subroutine call occupies two locations and an interrupt five locations in the stack area.

Figure 9. Stack Manipulation Example



SYSTEM INTEGRITY MANAGEMENT (Cont'd)

6.4.2 Auxiliary Voltage Detector (AVD)

The Voltage Detector function (AVD) is based on an analog comparison between a $V_{IT-(AVD)}$ and $V_{IT+(AVD)}$ reference value and the V_{DD} main supply. The V_{IT-} reference value for falling voltage is lower than the V_{IT+} reference value for rising voltage in order to avoid parasitic detection (hysteresis).

The output of the AVD comparator is directly readable by the application software through a real time status bit (AVDF) in the SICSR register. This bit is read only.

Caution: The AVD function is active only if the LVD is enabled through the option byte (see [Section 14.1 on page 150](#)).

6.4.2.1 Monitoring the V_{DD} Main Supply

The AVD voltage threshold value is relative to the selected LVD threshold configured by option byte (see

If the AVD interrupt is enabled, an interrupt is generated when the voltage crosses the $V_{IT+(AVD)}$ or $V_{IT-(AVD)}$ threshold (AVDF bit toggles).

In the case of a drop in voltage, the AVD interrupt acts as an early warning, allowing software to shut down safely before the LVD resets the microcontroller. See [Figure 16](#).

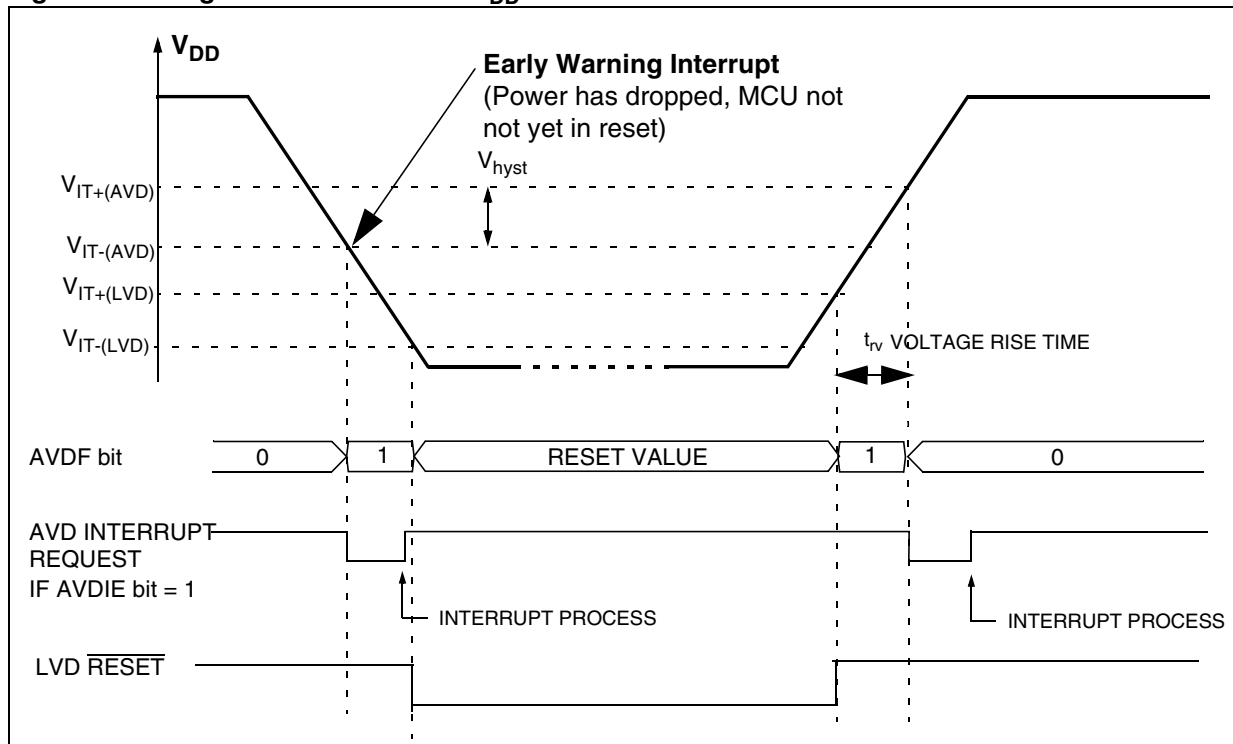
The interrupt on the rising edge is used to inform the application that the V_{DD} warning state is over.

If the voltage rise time t_{rv} is less than 256 or 4096 CPU cycles (depending on the reset delay selected by option byte), no AVD interrupt will be generated when $V_{IT+(AVD)}$ is reached.

If t_{rv} is greater than 256 or 4096 cycles then:

- If the AVD interrupt is enabled before the $V_{IT+(AVD)}$ threshold is reached, then 2 AVD interrupts will be received: the first when the AVDIE bit is set, and the second when the threshold is reached.
- If the AVD interrupt is enabled after the $V_{IT+(AVD)}$ threshold is reached then only one AVD interrupt will occur.

Figure 16. Using the AVD to Monitor V_{DD}



POWER SAVING MODES (Cont'd)

8.3 WAIT MODE

WAIT mode places the MCU in a low power consumption mode by stopping the CPU.

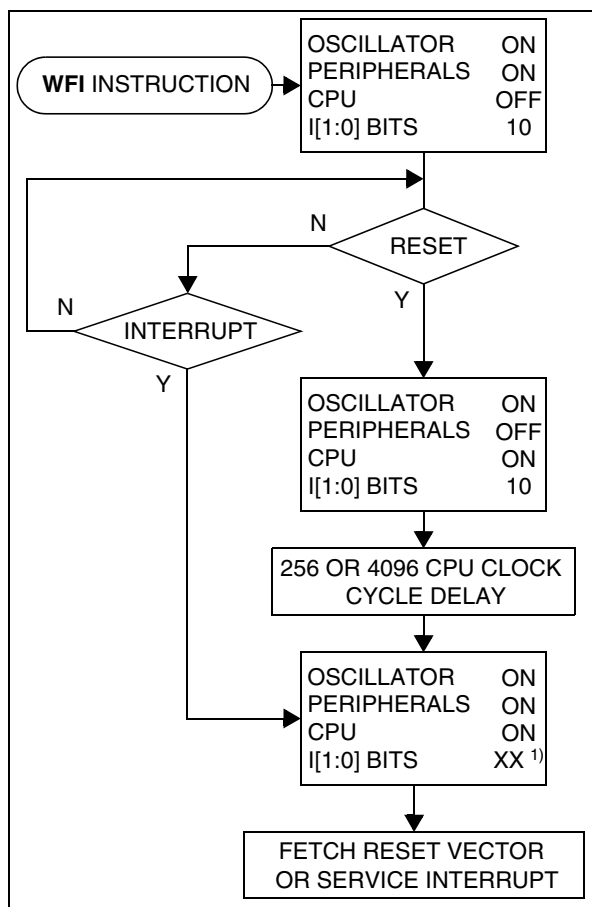
This power saving mode is selected by calling the 'WFI' instruction.

All peripherals remain active. During WAIT mode, the I[1:0] bits of the CC register are forced to '10', to enable all interrupts. All other registers and memory remain unchanged. The MCU remains in WAIT mode until an interrupt or RESET occurs, whereupon the Program Counter branches to the starting address of the interrupt or Reset service routine.

The MCU will remain in WAIT mode until a Reset or an Interrupt occurs, causing it to wake up.

Refer to [Figure 24](#).

Figure 24. WAIT Mode Flow-chart



Note:

1. Before servicing an interrupt, the CC register is pushed on the stack. The I[1:0] bits of the CC register are set to the current software priority level of the interrupt routine and recovered when the CC register is popped.

WATCHDOG TIMER (Cont'd)

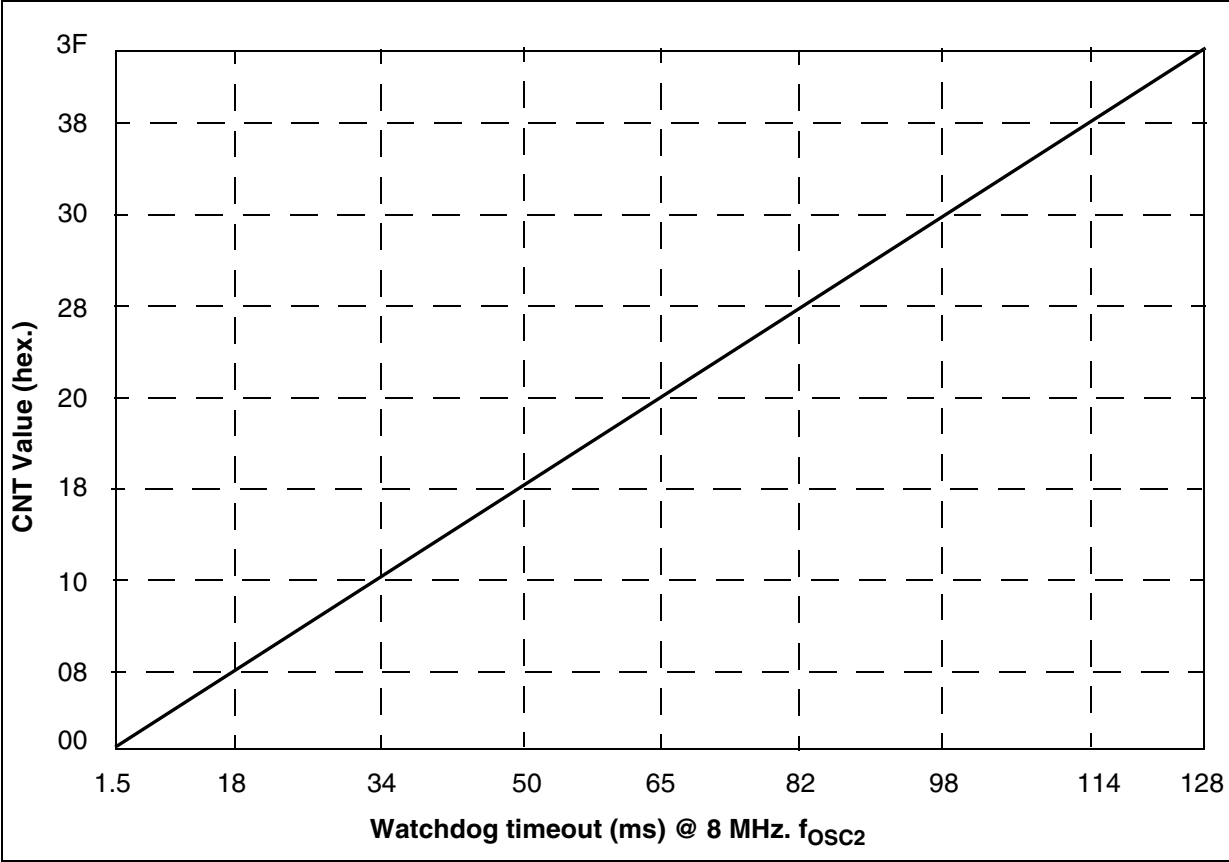
10.1.4 How to Program the Watchdog Timeout

Figure 32 shows the linear relationship between the 6-bit value to be loaded in the Watchdog Counter (CNT) and the resulting timeout duration in milliseconds. This can be used for a quick calculation without taking the timing variations into account. If

more precision is needed, use the formulae in Figure 33.

Caution: When writing to the WDGCR register, always write 1 in the T6 bit to avoid generating an immediate reset.

Figure 32. Approximate Timeout Duration



MAIN CLOCK CONTROLLER WITH REAL TIME CLOCK (Cont'd)

10.2.5 Low Power Modes

Mode	Description
WAIT	No effect on MCC/RTC peripheral. MCC/RTC interrupt cause the device to exit from WAIT mode.
ACTIVE-HALT	No effect on MCC/RTC counter (OIE bit is set), the registers are frozen. MCC/RTC interrupt cause the device to exit from ACTIVE-HALT mode.
HALT	MCC/RTC counter and registers are frozen. MCC/RTC operation resumes when the MCU is woken up by an interrupt with "exit from HALT" capability.

10.2.6 Interrupts

The MCC/RTC interrupt event generates an interrupt if the OIE bit of the MCCR register is set and the interrupt mask in the CC register is not active (RIM instruction).

Interrupt Event	Event Flag	Enable Control Bit	Exit from Wait	Exit from Halt
Time base overflow event	OIF	OIE	Yes	No ¹⁾

Note:

The MCC/RTC interrupt wakes up the MCU from ACTIVE-HALT mode, not from HALT mode.

10.2.7 Register Description

MCC CONTROL/STATUS REGISTER (MCCR)

Read/Write

Reset Value: 0000 0000 (00h)

7

0

MCO	CP1	CP0	SMS	TB1	TB0	OIE	OIF
-----	-----	-----	-----	-----	-----	-----	-----

Bit 7 = **MCO** Main clock out selection

This bit enables the MCO alternate function on the PF0 I/O port. It is set and cleared by software.

0: MCO alternate function disabled (I/O pin free for general-purpose I/O)

1: MCO alternate function enabled (f_{CPU} on I/O port)

Note: To reduce power consumption, the MCO function is not active in ACTIVE-HALT mode.

Bit 6:5 = **CP[1:0]** CPU clock prescaler

These bits select the CPU clock prescaler which is applied in the different slow modes. Their action is conditioned by the setting of the SMS bit. These two bits are set and cleared by software

f_{CPU} in SLOW mode	CP1	CP0
$f_{OSC2} / 2$	0	0
$f_{OSC2} / 4$	0	1
$f_{OSC2} / 8$	1	0
$f_{OSC2} / 16$	1	1

Bit 4 = **SMS** Slow mode select

This bit is set and cleared by software.

0: Normal mode. $f_{CPU} = f_{OSC2}$

1: Slow mode. f_{CPU} is given by CP1, CP0

See [Section 8.2 SLOW MODE](#) and [Section 10.2 MAIN CLOCK CONTROLLER WITH REAL TIME CLOCK AND BEEPER \(MCC/RTC\)](#) for more details.

Bit 3:2 = **TB[1:0]** Time base control

These bits select the programmable divider time base. They are set and cleared by software.

Counter Prescaler	Time Base		TB1	TB0
	$f_{OSC2} = 4\text{MHz}$	$f_{OSC2} = 8\text{MHz}$		
16000	4ms	2ms	0	0
32000	8ms	4ms	0	1
80000	20ms	10ms	1	0
200000	50ms	25ms	1	1

A modification of the time base is taken into account at the end of the current period (previously set) to avoid an unwanted time shift. This allows to use this time base as a real time clock.

Bit 1 = **OIE** Oscillator interrupt enable

This bit set and cleared by software.

0: Oscillator interrupt disabled

1: Oscillator interrupt enabled

This interrupt can be used to exit from ACTIVE-HALT mode.

When this bit is set, calling the ST7 software HALT instruction enters the ACTIVE-HALT power saving mode.

10.3 16-BIT TIMER

10.3.1 Introduction

The timer consists of a 16-bit free-running counter driven by a programmable prescaler.

It may be used for a variety of purposes, including pulse length measurement of up to two input signals (*input capture*) or generation of up to two output waveforms (*output compare* and *PWM*).

Pulse lengths and waveform periods can be modulated from a few microseconds to several milliseconds using the timer prescaler and the CPU clock prescaler.

Some ST7 devices have two on-chip 16-bit timers. They are completely independent, and do not share any resources. They are synchronized after a MCU reset as long as the timer clock frequencies are not modified.

This description covers one or two 16-bit timers. In ST7 devices with two timers, register names are prefixed with TA (Timer A) or TB (Timer B).

10.3.2 Main Features

- Programmable prescaler: f_{CPU} divided by 2, 4 or 8.
- Overflow status flag and maskable interrupt
- External clock input (must be at least 4 times slower than the CPU clock speed) with the choice of active edge
- 1 or 2 Output Compare functions each with:
 - 2 dedicated 16-bit registers
 - 2 dedicated programmable signals
 - 2 dedicated status flags
 - 1 dedicated maskable interrupt
- 1 or 2 Input Capture functions each with:
 - 2 dedicated 16-bit registers
 - 2 dedicated active edge selection signals
 - 2 dedicated status flags
 - 1 dedicated maskable interrupt
- Pulse width modulation mode (PWM)
- One pulse mode
- Reduced Power Mode
- 5 alternate functions on I/O ports (ICAP1, ICAP2, OCMP1, OCMP2, EXTCLK)*

The Block Diagram is shown in [Figure 35](#).

***Note:** Some timer pins may not be available (not bonded) in some ST7 devices. Refer to the device pin out description.

When reading an input signal on a non-bonded pin, the value will always be '1'.

10.3.3 Functional Description

10.3.3.1 Counter

The main block of the Programmable Timer is a 16-bit free running upcounter and its associated 16-bit registers. The 16-bit registers are made up of two 8-bit registers called high & low.

Counter Register (CR):

- Counter High Register (CHR) is the most significant byte (MS Byte).
- Counter Low Register (CLR) is the least significant byte (LS Byte).

Alternate Counter Register (ACR)

- Alternate Counter High Register (ACHR) is the most significant byte (MS Byte).
- Alternate Counter Low Register (ACLR) is the least significant byte (LS Byte).

These two read-only 16-bit registers contain the same value but with the difference that reading the ACLR register does not clear the TOF bit (Timer overflow flag), located in the Status register, (SR), (see note at the end of paragraph titled 16-bit read sequence).

Writing in the CLR register or ACLR register resets the free running counter to the FFFCh value. Both counters have a reset value of FFFCh (this is the only value which is reloaded in the 16-bit timer). The reset value of both counters is also FFFCh in One Pulse mode and PWM mode.

The timer clock depends on the clock control bits of the CR2 register, as illustrated in [Table 16 Clock Control Bits](#). The value in the counter register repeats every 131072, 262144 or 524288 CPU clock cycles depending on the CC[1:0] bits.

The timer frequency can be $f_{CPU}/2$, $f_{CPU}/4$, $f_{CPU}/8$ or an external frequency.

Caution: In Flash devices, Timer A functionality has the following restrictions:

- TAOC2HR and TAOC2LR registers are write only
- Input Capture 2 is not implemented
- The corresponding interrupts cannot be used (ICF2, OCF2 forced by hardware to zero)

16-BIT TIMER (Cont'd)

10.3.3.4 Output Compare

In this section, the index, i , may be 1 or 2 because there are 2 output compare functions in the 16-bit timer.

This function can be used to control an output waveform or indicate when a period of time has elapsed.

When a match is found between the Output Compare register and the free running counter, the output compare function:

- Assigns pins with a programmable value if the OC \bar{E} bit is set
- Sets a flag in the status register
- Generates an interrupt if enabled

Two 16-bit registers Output Compare Register 1 (OC1R) and Output Compare Register 2 (OC2R) contain the value to be compared to the counter register each timer clock cycle.

	MS Byte	LS Byte
OC \bar{R}	OC $\bar{H}R$	OC $\bar{L}R$

These registers are readable and writable and are not affected by the timer hardware. A reset event changes the OC \bar{R} value to 8000h.

Timing resolution is one count of the free running counter: ($f_{CPU}/CC[1:0]$).

Procedure:

To use the output compare function, select the following in the CR2 register:

- Set the OC \bar{E} bit if an output is needed then the OCMP \bar{i} pin is dedicated to the output compare i signal.
- Select the timer clock (CC[1:0]) (see [Table 16 Clock Control Bits](#)).

And select the following in the CR1 register:

- Select the OLVL \bar{i} bit to applied to the OCMP \bar{i} pins after the match occurs.
- Set the OCIE bit to generate an interrupt if it is needed.

When a match is found between OCR \bar{i} register and CR register:

- OCF \bar{i} bit is set.

- The OCMP \bar{i} pin takes OLVL \bar{i} bit value (OCMP \bar{i} pin latch is forced low during reset).
- A timer interrupt is generated if the OCIE bit is set in the CR1 register and the I bit is cleared in the CC register (CC).

The OC \bar{R} register value required for a specific timing application can be calculated using the following formula:

$$\Delta OC\bar{R} = \frac{\Delta t * f_{CPU}}{PRESC}$$

Where:

Δt = Output compare period (in seconds)

f_{CPU} = CPU clock frequency (in hertz)

PRESC = Timer prescaler factor (2, 4 or 8 depending on CC[1:0] bits, see [Table 16 Clock Control Bits](#))

If the timer clock is an external clock, the formula is:

$$\Delta OC\bar{R} = \Delta t * f_{EXT}$$

Where:

Δt = Output compare period (in seconds)

f_{EXT} = External timer clock frequency (in hertz)

Clearing the output compare interrupt request (i.e. clearing the OCF \bar{i} bit) is done by:

1. Reading the SR register while the OCF \bar{i} bit is set.
2. An access (read or write) to the OC $\bar{L}R$ register.

The following procedure is recommended to prevent the OCF \bar{i} bit from being set between the time it is read and the write to the OC \bar{R} register:

- Write to the OC $\bar{H}R$ register (further compares are inhibited).
- Read the SR register (first step of the clearance of the OCF \bar{i} bit, which may be already set).
- Write to the OC $\bar{L}R$ register (enables the output compare function and clears the OCF \bar{i} bit).

SERIAL COMMUNICATIONS INTERFACE (Cont'd)**DATA REGISTER (SCIDR)**

Read/Write

Reset Value: Undefined

Contains the Received or Transmitted data character, depending on whether it is read from or written to.

7							0
DR7	DR6	DR5	DR4	DR3	DR2	DR1	DR0

The Data register performs a double function (read and write) since it is composed of two registers, one for transmission (TDR) and one for reception (RDR).

The TDR register provides the parallel interface between the internal bus and the output shift register (see [Figure 1.](#)).

The RDR register provides the parallel interface between the input shift register and the internal bus (see [Figure 1.](#)).

BAUD RATE REGISTER (SCIBRR)

Read/Write

Reset Value: 0000 0000 (00h)

7							0
SCP1	SCP0	SCT2	SCT1	SCT0	SCR2	SCR1	SCR0

Bits 7:6 = **SCP[1:0]** *First SCI Prescaler*

These 2 prescaling bits allow several standard clock division ranges:

PR Prescaling factor	SCP1	SCP0
1	0	0
3	0	1
4	1	0
13	1	1

Bits 5:3 = **SCT[2:0]** *SCI Transmitter rate divisor*

These 3 bits, in conjunction with the SCP1 & SCP0 bits define the total division applied to the bus clock to yield the transmit rate clock in conventional Baud Rate Generator mode.

TR dividing factor	SCT2	SCT1	SCT0
1	0	0	0
2	0	0	1
4	0	1	0
8	0	1	1
16	1	0	0
32	1	0	1
64	1	1	0
128	1	1	1

Bits 2:0 = **SCR[2:0]** *SCI Receiver rate divisor.*

These 3 bits, in conjunction with the SCP[1:0] bits define the total division applied to the bus clock to yield the receive rate clock in conventional Baud Rate Generator mode.

RR Dividing factor	SCR2	SCR1	SCR0
1	0	0	0
2	0	0	1
4	0	1	0
8	0	1	1
16	1	0	0
32	1	0	1
64	1	1	0
128	1	1	1

SERIAL COMMUNICATIONS INTERFACE (Cont'd)**EXTENDED RECEIVE PRESCALER DIVISION REGISTER (SCIERPR)**

Read/Write

Reset Value: 0000 0000 (00h)

Allows setting of the Extended Prescaler rate division factor for the receive circuit.

7							0
ERPR 7	ERPR 6	ERPR 5	ERPR 4	ERPR 3	ERPR 2	ERPR 1	ERPR 0

Bits 7:0 = **ERPR[7:0]** 8-bit Extended Receive Prescaler Register.

The extended Baud Rate Generator is activated when a value different from 00h is stored in this register. Therefore the clock frequency issued from the 16 divider (see [Figure 3.](#)) is divided by the binary factor set in the SCIERPR register (in the range 1 to 255).

The extended baud rate generator is not used after a reset.

EXTENDED TRANSMIT PRESCALER DIVISION REGISTER (SCIETPR)

Read/Write

Reset Value: 0000 0000 (00h)

Allows setting of the External Prescaler rate division factor for the transmit circuit.

7							0
ETPR 7	ETPR 6	ETPR 5	ETPR 4	ETPR 3	ETPR 2	ETPR 1	ETPR 0

Bits 7:0 = **ETPR[7:0]** 8-bit Extended Transmit Prescaler Register.

The extended Baud Rate Generator is activated when a value different from 00h is stored in this register. Therefore the clock frequency issued from the 16 divider (see [Figure 3.](#)) is divided by the binary factor set in the SCIETPR register (in the range 1 to 255).

The extended baud rate generator is not used after a reset.

Table 21. Baudrate Selection

Symbol	Parameter	Conditions			Standard	Baud Rate	Unit
		f _{CPU}	Accuracy vs Standard	Prescaler			
f _{Tx} f _{Rx}	Communication frequency	8 MHz	~0.16%	Conventional Mode TR (or RR)=128, PR=13 TR (or RR)= 32, PR=13 TR (or RR)= 16, PR=13 TR (or RR)= 8, PR=13 TR (or RR)= 4, PR=13 TR (or RR)= 16, PR= 3 TR (or RR)= 2, PR=13 TR (or RR)= 1, PR=13	300 1200 2400 4800 9600 10400 19200 38400	~300.48 ~1201.92 ~2403.84 ~4807.69 ~9615.38 ~10416.67 ~19230.77 ~38461.54	Hz
			~0.79%	Extended Mode ETPR (or ERPR) = 35, TR (or RR)= 1, PR=1	14400	~14285.71	

10-BIT A/D CONVERTER (Cont'd)**Table 23. ADC Register Map and Reset Values**

Address (Hex.)	Register Label	7	6	5	4	3	2	1	0
0070h	ADCCSR Reset Value	EOC 0	SPEED 0	ADON 0	0	CH3 0	CH2 0	CH1 0	CH0 0
0071h	ADCDRH Reset Value	D9 0	D8 0	D7 0	D6 0	D5 0	D4 0	D3 0	D2 0
0072h	ADCDRL Reset Value	0	0	0	0	0	0	D1 0	D0 0

INSTRUCTION SET OVERVIEW (Cont'd)**11.1.6 Indirect Indexed (Short, Long)**

This is a combination of indirect and short indexed addressing modes. The operand is referenced by its memory address, which is defined by the unsigned addition of an index register value (X or Y) with a pointer value located in memory. The pointer address follows the opcode.

The indirect indexed addressing mode consists of two sub-modes:

Indirect Indexed (Short)

The pointer address is a byte, the pointer size is a byte, thus allowing 00 - 1FE addressing space, and requires 1 byte after the opcode.

Indirect Indexed (Long)

The pointer address is a byte, the pointer size is a word, thus allowing 64 Kbyte addressing space, and requires 1 byte after the opcode.

Table 25. Instructions Supporting Direct, Indexed, Indirect and Indirect Indexed Addressing Modes

Long and Short Instructions	Function
LD	Load
CP	Compare
AND, OR, XOR	Logical Operations
ADC, ADD, SUB, SBC	Arithmetic Additions/Subtractions operations
BCP	Bit Compare

Short Instructions Only	Function
CLR	Clear
INC, DEC	Increment/Decrement
TNZ	Test Negative or Zero
CPL, NEG	1 or 2 Complement
BSET, BRES	Bit Operations
BTJT, BTJF	Bit Test and Jump Operations
SLL, SRL, SRA, RLC, RRC	Shift and Rotate Operations
SWAP	Swap Nibbles
CALL, JP	Call or Jump subroutine

11.1.7 Relative mode (Direct, Indirect)

This addressing mode is used to modify the PC register value, by adding an 8-bit signed offset to it.

Available Relative Direct/Indirect Instructions	Function
JRxx	Conditional Jump
CALLR	Call Relative

The relative addressing mode consists of two sub-modes:

Relative (Direct)

The offset is following the opcode.

Relative (Indirect)

The offset is defined in memory, which address follows the opcode.

INSTRUCTION SET OVERVIEW (Cont'd)

11.2 INSTRUCTION GROUPS

The ST7 family devices use an Instruction Set consisting of 63 instructions. The instructions may

be subdivided into 13 main groups as illustrated in the following table:

Load and Transfer	LD	CLR						
Stack operation	PUSH	POP	RSP					
Increment/Decrement	INC	DEC						
Compare and Tests	CP	TNZ	BCP					
Logical operations	AND	OR	XOR	CPL	NEG			
Bit Operation	BSET	BRES						
Conditional Bit Test and Branch	BTJT	BTJF						
Arithmetic operations	ADC	ADD	SUB	SBC	MUL			
Shift and Rotates	SLL	SRL	SRA	RLC	RRC	SWAP	SLA	
Unconditional Jump or Call	JRA	JRT	JRF	JP	CALL	CALLR	NOP	RET
Conditional Branch	JRxx							
Interrupt management	TRAP	WFI	HALT	IRET				
Condition Code Flag modification	SIM	RIM	SCF	RCF				

Using a pre-byte

The instructions are described with one to four opcodes.

In order to extend the number of available opcodes for an 8-bit CPU (256 opcodes), three different prebyte opcodes are defined. These prebytes modify the meaning of the instruction they precede.

The whole instruction becomes:

PC-2 End of previous instruction
 PC-1 Prebyte
 PC opcode
 PC+1 Additional word (0 to 2) according to the number of bytes required to compute the effective address

These prebytes enable instruction in Y as well as indirect addressing modes to be implemented. They precede the opcode of the instruction in X or the instruction using direct addressing mode. The prebytes are:

PDY 90 Replace an X based instruction using immediate, direct, indexed, or inherent addressing mode by a Y one.

PIX 92 Replace an instruction using direct, direct bit, or direct relative addressing mode to an instruction using the corresponding indirect addressing mode.

It also changes an instruction using X indexed addressing mode to an instruction using indirect X indexed addressing mode.

PIY 91 Replace an instruction using X indirect indexed addressing mode by a Y one.

SUPPLY CURRENT CHARACTERISTICS (Cont'd)**12.5.2 Supply and Clock Managers**

The previous current consumption specified for the ST7 functional operating modes over temperature range does not take into account the clock source current consumption. To get the total device consumption, the two current values must be added (except for HALT mode).

Symbol	Parameter	Conditions	Typ	Max	Unit
I _{DD(RCINT)}	Supply current of internal RC oscillator		625		μA
I _{DD(RES)}	Supply current of resonator oscillator ¹⁾ & ²⁾		see Section 12.6.3 on page 125		
I _{DD(PLL)}	PLL supply current	V _{DD} = 5V	360		μA
I _{DD(LVD)}	LVD supply current	V _{DD} = 5V	150	300	

Notes:

1. Data based on characterization results done with the external components specified in [Section 12.6.3](#), not tested in production.
2. As the oscillator is based on a current source, the consumption does not depend on the voltage.

CLOCK AND TIMING CHARACTERISTICS (Cont'd)

Oscil.		Typical Ceramic Resonators (information for guidance only)			C _{L1}	C _{L2}	t _{SU(osc)}
		Reference ³⁾	Freq.	Characteristic ¹⁾	[pF]	[pF]	[ms] ²⁾
Ceramic	LP	CSA2.00MG	2MHz	$\Delta f_{OSC} = [\pm 0.5\%_{\text{tolerance}}, \pm 0.3\%_{\Delta T_a}, \pm 0.3\%_{\text{aging}}, \pm x.x\%_{\text{correl}}]$	22	22	4
	MP	CSA4.00MG	4MHz	$\Delta f_{OSC} = [\pm 0.5\%_{\text{tolerance}}, \pm 0.3\%_{\Delta T_a}, \pm 0.3\%_{\text{aging}}, \pm x.x\%_{\text{correl}}]$	22	22	2
	MS	CSA8.00MTZ	8MHz	$\Delta f_{OSC} = [\pm 0.5\%_{\text{tolerance}}, \pm 0.5\%_{\Delta T_a}, \pm 0.3\%_{\text{aging}}, \pm x.x\%_{\text{correl}}]$	33	33	1
	HS	CSA16.00MXZ040 ⁴⁾	16MHz	$\Delta f_{OSC} = [\pm 0.5\%_{\text{tolerance}}, \pm 0.3\%_{\Delta T_a}, \pm 0.3\%_{\text{aging}}, \pm x.x\%_{\text{correl}}]$	33	33	0.7

Notes:

1. Resonator characteristics given by the ceramic resonator manufacturer.
2. t_{SU(OSC)} is the typical oscillator start-up time measured between V_{DD}=2.8V and the fetch of the first instruction (with a quick V_{DD} ramp-up from 0 to 5V (<50μs).
3. Resonators all have different characteristics. Contact the manufacturer to obtain the appropriate values of external components and to verify oscillator performance.
4. 3rd overtone resonators require specific validation by the resonator manufacturer.

PACKAGE MECHANICAL DATA (Cont'd)

Figure 90. 42-Pin Plastic Dual In-Line Package, Shrink 600-mil Width

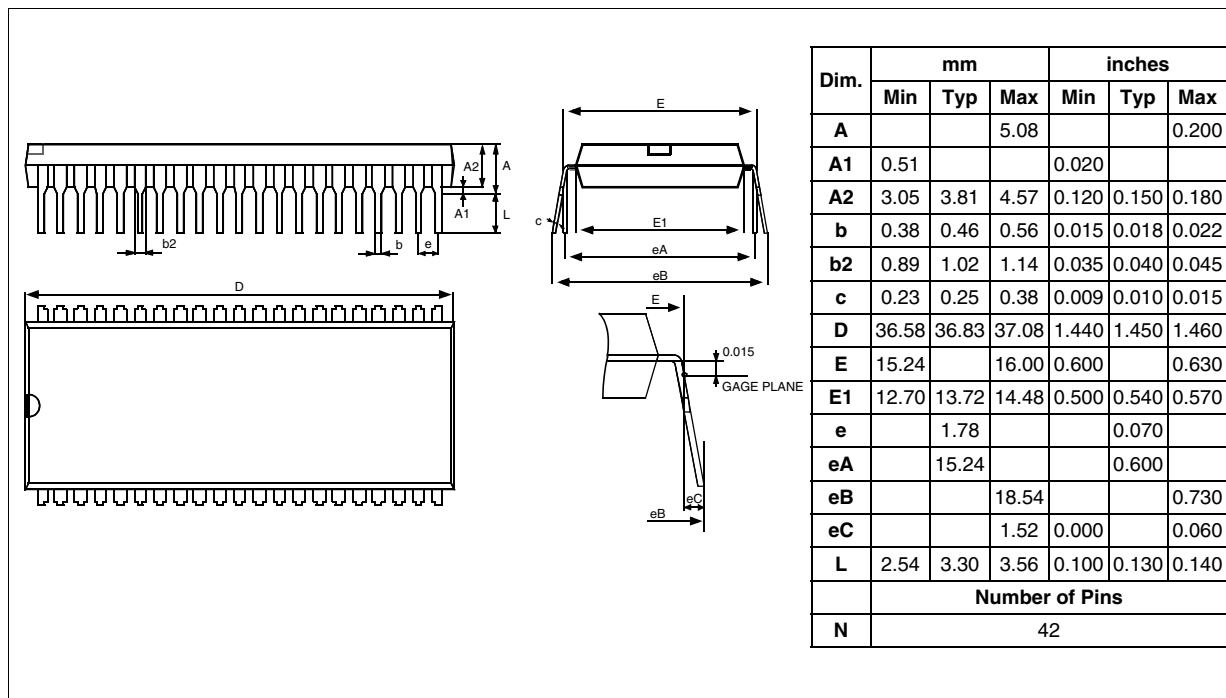
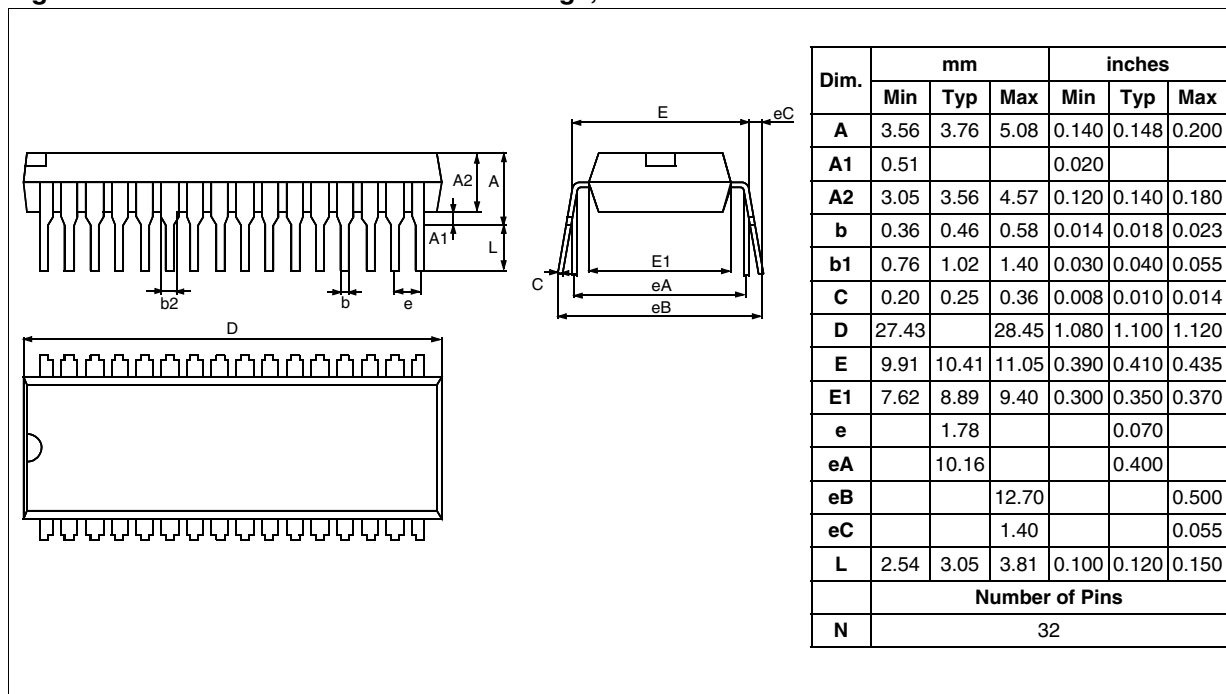


Figure 91. 32-Pin Plastic Dual In-Line Package, Shrink 400-mil Width



DEVICE CONFIGURATION AND ORDERING INFORMATION (Cont'd)**Table 26. Standard and Industrial ST72F324 Flash Order Codes**

Part Number	Package	Flash Memory (KBytes)	Temp. Range
ST72F324K2B5	SDIP32	8	-10°C +85°C
ST72F324K4B5		16	
ST72F324K6B5		32	
ST72F324J6B5	SDIP42	32	
ST72F324K6T5	TQFP32	32	-10°C +85°C
ST72F324K2T6		8	-40°C +85°C
ST72F324K4T6		16	
ST72F324K6T6		32	
ST72F324K2T3		8	-40°C +125°C
ST72F324K4T3		16	
ST72F324K6T3		32	
ST72F324J6T5	TQFP44	32	-10°C +85°C
ST72F324J2T6		8	-40°C +85°C
ST72F324J4T6		16	
ST72F324J6T6		32	
ST72F324J2T3		8	-40°C +125°C
ST72F324J4T3		16	
ST72F324J6T3		32	

14.4.1 Socket and Emulator Adapter Information

For information on the type of socket that is supplied with the emulator, refer to the suggested list of sockets in [Table 29](#).

Note: Before designing the board layout, it is recommended to check the overall dimensions of the socket as they may be greater than the dimensions of the device.

For footprint and other mechanical information about these sockets and adapters, refer to the manufacturer's datasheet (www.yamaichi.de for TQFP44 10 x 10 and www.ironwoodelectronics.com for TQFP32 7 x 7).

Table 29. Suggested List of Socket Types

Device	Socket (supplied with ST7MDT20J-EMU3)	Emulator Adapter (supplied with ST7MDT20J-EMU3)
TQFP32 7 X 7	IRONWOOD SF-QFE32SA-L-01	IRONWOOD SK-UGA06/32A-01
TQFP44 10 X10	YAMAICHI IC149-044-*52-*5	YAMAICHI ICP-044-5

16 IMPORTANT NOTES ON ST72F324B FLASH DEVICES:

With the objective of continuous improvement, ST has developed new ST72F324B devices. These devices are fully compatible with all ROM features and provide an improved price/performance ratio compared to the ST72F324 flash devices.

A summary of the technical improvements is given below.

Refer to separate ST72324B datasheet for the ordering information and full specifications.

16.1 Reset Pin Logic levels

In ST72F324B Flash devices, the V_{IH}/V_{IL} levels for the reset pin are the same as specified for ROM devices

16.2 Wake-Up from Active Halt mode using external interrupts

In ST72F324B Flash devices, any external interrupt that capable of waking-up the MCU from Halt mode can also wake-up the MCU from Active Halt mode. Consequently note 1 below [Table 8 on page 36](#) does not apply to 'B' devices.

16.3 PLL Jitter

In ST72F324B Flash devices, PLL clock accuracy is improved and the jitter is the same as specified for ROM devices

16.4 Active Halt Power Consumption

In ST72F324B Flash devices, the power consumption in Active Halt mode is specified as 230µA max. See [Table 12.5.1 on page 120](#) for test conditions.

16.5 Timer A Registers

In ST72F324B Flash devices, all Timer A registers are present and their functionality is the same as described for ROM devices in the ST72324B datasheet.